

MEMORY

Unbuffered

144-PIN SO DIMM 2 M × 64 BITS HYPER PAGE MODE DRAM MODULE

MB8502E064AA-60/-70/-60L/-70L

Unbuffered, 2 M × 64 BITS Hyper Page Mode SO DIMM, 3.3 V, 1-bank, 2 KR

DESCRIPTION

The Fujitsu MB8502E064AA is a fully decoded, CMOS Dynamic Random Access Memory (DRAM) module consisting of eight MB81V17805A devices. The MB8502E064AA is optimized for those applications requiring small size package, low power consumption, enhanced performance. The operation and electrical characteristics of the MB8502E064AA are the same as the MB81V17805A which features hyper page mode (EDO) operation. For ease of memory expansion, the MB8502E064AA is offered in an 144-pin Small Outline Dual In-line Memory Module package (SO DIMM).

PRODUCT LINE & FEATURES

Parameter		MB8502E064AA			
		-60	-60L	-70	-70L
RAS Access Time		60 ns max.		70 ns max.	
Random Cycle Time		104 ns min.		125 ns min.	
Address Access Time		30 ns max.		35 ns max.	
CAS Access Time		15 ns max.		17 ns max.	
Hyper Page Mode Cycle Time		25 ns min.		30 ns min.	
Power Dissipation	Operating Mode	3456 mW max.		3168 mW max.	
	Standby Mode	57.6 mW max.	28.8 mW max.	57.6 mW max.	28.8 mW max.

- Conformed to 144-pin SO DIMM JEDEC standard
- Organization : 2,097,152 words × 64 bits
- Module Size : 1.00" (height) × 2.66" (length) × 0.15" (thick)
- Memory : MB81V17805A (2 M × 8, 2 K ref., 3.3 V) 8 pcs
- 3.3 V ± 0.3 V Supply Voltage
- 2,048 Refresh Cycles / 32.8 ms
- Hyper Page Operation (EDO)
- Serial Presence Detect
- RAS-Only Refresh / CAS-before-RAS Refresh
- Package and Ordering Information:
144-pin SO DIMM, order as
MB8502E064AA-xxDG
(DG = Gold Pad)

This device contains circuitry to protect the inputs against damage due to high static voltages or electric fields. However, it is advised that normal precautions be taken to avoid application of any voltage higher than maximum rated voltages to this high-impedance circuit.

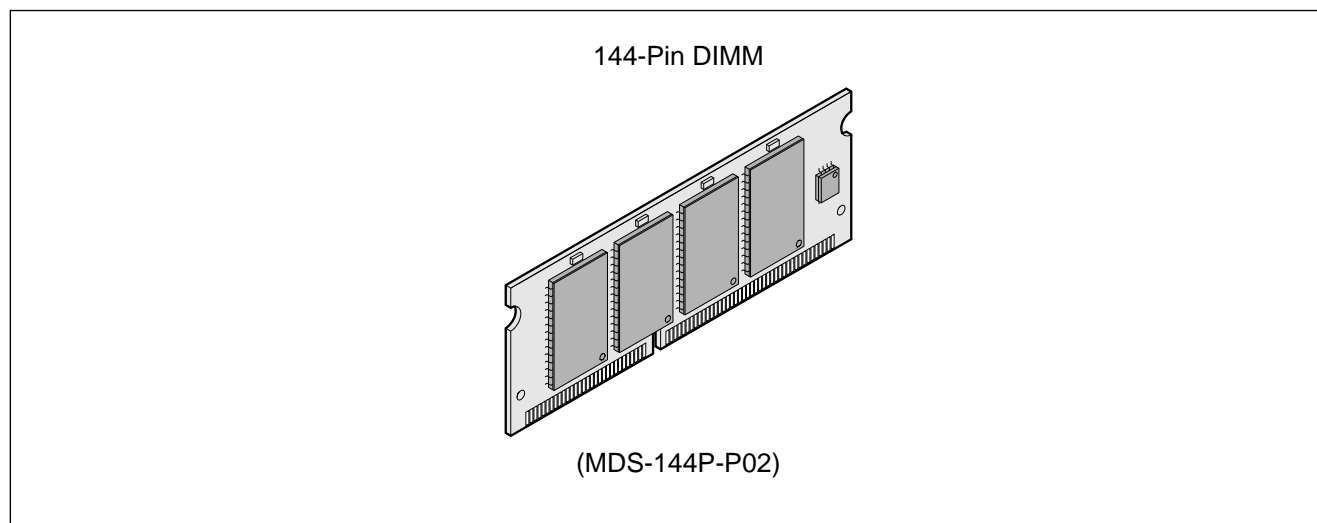
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■ ABSOLUTE MAXIMUM RATINGS (See WARNING)

Parameter	Symbol	Value	Unit
Supply Voltage	V_{CC}	-0.5 to +4.6	V
Input Voltage	V_{IN}	-0.5 to +4.6	V
Output Voltage	V_{OUT}	-0.5 to +4.6	V
Short Circuit Output Current	I_{OUT}	-50 to +50	mA
Power Dissipation	P_D	8	W
Storage Temperature	T_{STG}	-55 to +125	°C

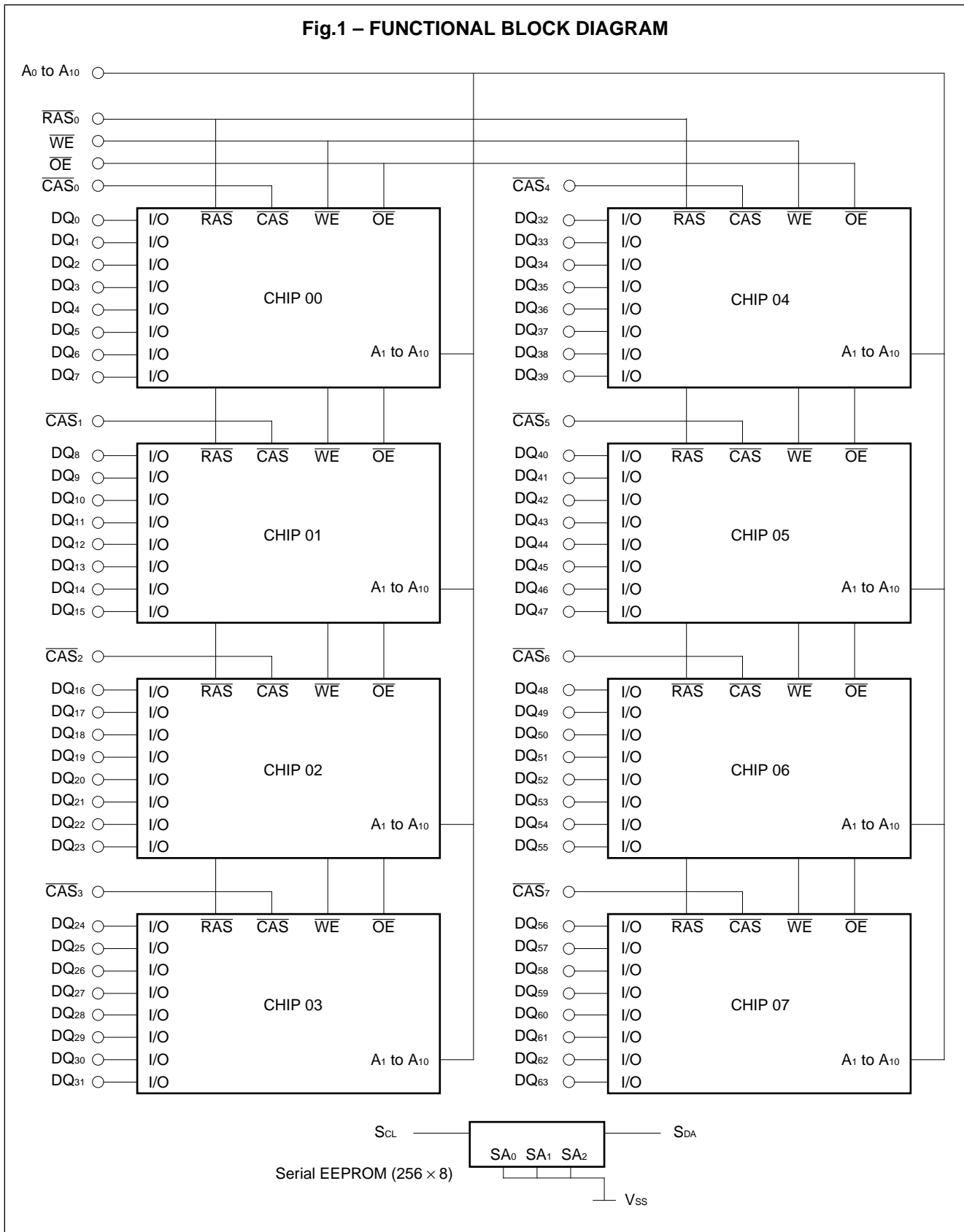
WARNING: Permanent device damage may occur if the above **Absolute Maximum Ratings** are exceeded. Functional operation should be restricted to the conditions as detailed in the operational sections of this data sheet. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

■ PACKAGE



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Fig.1 – FUNCTIONAL BLOCK DIAGRAM



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■ PIN ASSIGNMENTS

Pin No.	MB8502E064AA	Pin No.	MB8502E064AA	Pin No.	MB8502E064AA	Pin No.	MB8502E064AA
1	V _{SS}	37	DQ ₈	73	\overline{OE}	109	A ₉
2	V _{SS}	38	DQ ₄₀	74	N.C.	110	N.C.
3	DQ ₀	39	DQ ₉	75	V _{SS}	111	A ₁₀
4	DQ ₃₂	40	DQ ₄₁	76	V _{SS}	112	N.C.
5	DQ ₁	41	DQ ₁₀	77	N.C.	113	V _{CC}
6	DQ ₃₃	42	DQ ₄₂	78	N.C.	114	V _{CC}
7	DQ ₂	43	DQ ₁₁	79	N.C.	115	\overline{CAS}_2
8	DQ ₃₄	44	DQ ₄₃	80	N.C.	116	\overline{CAS}_6
9	DQ ₃	45	V _{CC}	81	V _{CC}	117	\overline{CAS}_3
10	DQ ₃₅	46	V _{CC}	82	V _{CC}	118	\overline{CAS}_7
11	V _{CC}	47	DQ ₁₂	83	DQ ₁₆	119	V _{SS}
12	V _{CC}	48	DQ ₄₄	84	DQ ₄₈	120	V _{SS}
13	DQ ₄	49	DQ ₁₃	85	DQ ₁₇	121	DQ ₂₄
14	DQ ₃₆	50	DQ ₄₅	86	DQ ₄₉	122	DQ ₅₆
15	DQ ₅	51	DQ ₁₄	87	DQ ₁₈	123	DQ ₂₅
16	DQ ₃₇	52	DQ ₄₆	88	DQ ₅₀	124	DQ ₅₇
17	DQ ₆	53	DQ ₁₅	89	DQ ₁₉	125	DQ ₂₆
18	DQ ₃₈	54	DQ ₄₇	90	DQ ₅₁	126	DQ ₅₈
19	DQ ₇	55	V _{SS}	91	V _{SS}	127	DQ ₂₇
20	DQ ₃₉	56	V _{SS}	92	V _{SS}	128	DQ ₅₉
21	V _{SS}	57	N.C.	93	DQ ₂₀	129	V _{CC}
22	V _{SS}	58	N.C.	94	DQ ₅₂	130	V _{CC}
23	\overline{CAS}_0	59	N.C.	95	DQ ₂₁	131	DQ ₂₈
24	\overline{CAS}_4	60	N.C.	96	DQ ₅₃	132	DQ ₆₀
25	\overline{CAS}_1	61	N.C.	97	DQ ₂₂	133	DQ ₂₉
26	\overline{CAS}_5	62	N.C.	98	DC ₅₄	134	DC ₆₁
27	V _{CC}	63	V _{CC}	99	DC ₂₃	135	DC ₃₀
28	V _{CC}	64	V _{CC}	100	DC ₅₅	136	DC ₆₂
29	A ₀	65	N.C.	101	V _{CC}	137	DQ ₃₁
30	A ₃	66	N.C.	102	V _{CC}	138	DQ ₆₃
31	A ₁	67	\overline{WE}	103	A ₆	139	V _{SS}
32	A ₄	68	N.C.	104	A ₇	140	V _{SS}
33	A ₂	69	\overline{RAS}_0	105	A ₈	141	SDA
34	A ₅	70	N.C.	106	N.C.	142	SCL
35	V _{SS}	71	N.C.	107	V _{SS}	143	V _{CC}
36	V _{SS}	72	N.C.	108	V _{SS}	144	V _{CC}

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■ PIN DESCRIPTIONS

Symbol	Function	Input/Output	Pin Count
A ₀ to A ₁₀	Address Input	Input	11
$\overline{\text{RAS}}_0$	Row Address Strobe	Input	1
$\overline{\text{CAS}}_0$ to $\overline{\text{CAS}}_7$	Column Address Strobe	Input	8
$\overline{\text{WE}}$	Write Enable	Input	1
$\overline{\text{OE}}$	Output Enable	Input	1
DQ ₀ to DQ ₆₃	Data-input/Data-output	Input/Output	64
SCL	Serial PD Clock	Input	1
SDA	Serial PD I/O	Input/Output	1
V _{CC}	Power Supply	—	18
V _{SS}	Ground	—	18
N.C.	No Connection	—	20

■ SERIAL PRESENCE DETECT (SPD) TABLE

Byte	Function Described		Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
0	Number of Bytes Used by Module Manufacturer	12 Bytes	0	0	0	0	1	1	0	0
1	Total SPD Memory Size	256 Bytes	0	0	0	0	1	0	0	0
2	Memory Type	EDO	0	0	0	0	0	0	1	0
3	Number of Row Addresses	11 Addresses	0	0	0	0	1	0	1	1
4	Number of Column Addresses	10 Addresses	0	0	0	0	1	0	1	0
5	Number of Banks	1 Bank	0	0	0	0	0	0	0	1
6	Module Data Width (1)	64 Bits	0	1	0	0	0	0	0	0
7	Module Data Width (2)	+0 Bits	0	0	0	0	0	0	0	0
8	Module Interface Levels	LVTTTL	0	0	0	0	0	0	0	1
9	$\overline{\text{RAS}}$ Access Time (t _{RAC})	60 ns	0	0	1	1	1	1	0	0
		70 ns	0	1	0	0	0	1	1	0
10	$\overline{\text{CAS}}$ Access Time (t _{CAC})	15 ns	0	0	0	0	1	1	1	1
		17 ns	0	0	0	1	0	0	0	1
11	Module Configuration Type (Parity or ECC or None)	None	0	0	0	0	0	0	0	0
12	Refresh Rate / Type	Normal, Self Refresh	1	0	0	0	0	0	0	0
		Low Power, Self Refresh	1	0	0	0	0	1	0	0
13 to 31	Reserved for Future Offerings	—	—	—	—	—	—	—	—	—
32 to 63	Superset Information	—	—	—	—	—	—	—	—	—
64 to 127	Manufacturer's Information	—	—	—	—	—	—	—	—	—
128 to 255	Unused Storage Locations	—	—	—	—	—	—	—	—	—

Note: Any write operation must NOT be executed into the addresses of Byte 0 to Byte 127. Some or all data stored into Byte 0 to Byte 127 may be broken.

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■ CAPACITANCE

($T_A = 25^\circ\text{C}$, $f = 1\text{ MHz}$, $V_{CC} = +3.3\text{ V}$)

Parameter	Symbol	Min.	Max.	Unit	
Input Capacitance	A_0 to A_{10}	C_{IN1}	—	54	pF
	\overline{RAS}_0	C_{IN2}	—	52	pF
	\overline{CAS}_0 to \overline{CAS}_7	C_{IN3}	—	12	pF
	\overline{WE}	C_{IN4}	—	52	pF
	\overline{OE}	C_{IN5}	—	53	pF
	SCL	C_{IN6}	—	5	pF
I/O Capacitance	DQ ₀ to DQ ₆₃	C_{DQ}	—	10	pF
	SDA	C_{SDA}	—	5	pF

■ RECOMMENDED OPERATING CONDITIONS

(Referenced to V_{SS})

Parameter	Symbol	Min.	Typ.	Max.	Unit
Supply Voltage	V_{CC}	3.0	3.0	3.6	V
Ground	V_{SS}	—	0	—	V
Input High Voltage, all inputs	V_{IH}	2.0	—	$V_{CC} + 0.3\text{ V}$	V
Input Low Voltage, all inputs*	V_{IL}	-0.3	—	0.8	V
Ambient Temperature	T_A	0	—	70	$^\circ\text{C}$

Note: * Undershoots of up to -2.0 volts with a pulse width not exceeding 20 ns are acceptable.

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■ DC CHARACTERISTICS

(At recommended operating conditions unless otherwise noted.)

Parameter	Notes	Symbol	Condition	Value			Unit
				Min.	Max.		
					-60/-70	-60L/-70L	
Output High Voltage	*1	V_{OH}	$I_{OH} = -2.0 \text{ mA}$	2.4	—		V
Output Low Voltage	*1	V_{OL}	$I_{OL} = 2.0 \text{ mA}$	—	0.4		V
Input Leakage Current	CAS	$I_{I(L)}$	$0 \text{ V} \leq V_{IN} \leq V_{CC}$, $3.0 \text{ V} \leq V_{CC} \leq 3.6 \text{ V}$, $V_{SS} = 0 \text{ V}$, all other pins not under test = 0 V	-10	10		μA
	Others			-50	50		
Output Leakage Current		$I_{O(L)}$	$0 \text{ V} \leq V_{OUT} \leq V_{CC}$, $3.0 \text{ V} \leq V_{CC} \leq 3.6 \text{ V}$ Data out disabled	-10	10		μA
Operating Current (Average Power Supply Current)	*2	I_{CC1}	RAS & CAS cycling, $t_{RC} = \text{min}$	—	960		mA
				—	880		
Standby Current (Power Supply Current)	*2	I_{CC2}	RAS = CAS = V_{IH} RAS = CAS $\geq V_{CC} - 0.2 \text{ V}$	—	16	8	mA
				—	8	1.2	
Refresh Current #1 (Average Power Supply Current)	*2	I_{CC3}	CAS = V_{IH} , RAS = cycling, $t_{RC} = \text{min}$	—	960		mA
				—	880		
Hyper Page Mode Current	*2	I_{CC4}	RAS = V_{IL} , CAS = cycling, $t_{HPC} = \text{min}$	—	960		mA
				—	880		
Refresh Current #2 (Average Power Supply Current)	*2	I_{CC5}	RAS cycling, CAS-before-RAS, $t_{RC} = \text{min}$	—	960		mA
				—	880		
Battery Backup Current (Average Power Supply Current)	*2	I_{CC6}	RAS cycling, CAS-before-RAS, $t_{RAS} = \text{min to } 300 \text{ ns}$ $V_{IH} \geq V_{CC} - 0.2 \text{ V}$, $V_{IL} \leq 0.2 \text{ V}$, $t_{RC} = 16 \mu\text{s}$	—	8	—	mA
				—	—	2.4	mA
Refresh Current #3 (Average Power Supply Current)		I_{CC9}	Self-Refresh;	—	8	2	mA

Notes: *1. Referenced to V_{SS} .

*2. I_{CC} depends on the output load conditions and cycle rate. The specific values are obtained with the output open.

I_{CC} depends on the number of address change as RAS = V_{IL} and CAS = V_{IH} and $V_{IL} > -0.3 \text{ V}$.

I_{CC1} , I_{CC3} , I_{CC4} and I_{CC5} are specified at one time of address change during RAS = V_{IL} and CAS = V_{IH} .

I_{CC2} are specified during RAS = V_{IH} and $V_{IL} > -0.3 \text{ V}$. I_{CC6} is measured on condition that all address signals are fixed steady state.

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■ AC CHARACTERISTICS

(At recommended operating conditions unless otherwise noted.) Notes 1, 2, 3

No.	Parameter	Notes	Symbol	MB8502E064AA-60/-60L		MB8502E064AA-70/-70L		Unit
				Min.	Max.	Min.	Max.	
1	Time Between Refresh	-60/-70	t _{REF}	—	32.8	—	32.8	ms
		-60L/-70L		—	128	—	128	ms
2	Random Read/Write Cycle Time		t _{RC}	104	—	124	—	ns
3	Read-Modify-Write Cycle Time		t _{RWC}	138	—	162	—	ns
4	Access Time from $\overline{\text{RAS}}$	*4,7	t _{RAC}	—	60	—	70	ns
5	Access Time from $\overline{\text{CAS}}$	*5,7	t _{CAC}	—	15	—	17	ns
6	Column Address Access Time	*6,7	t _{AA}	0	30	—	35	ns
7	Output Hold Time		t _{OH}	3	—	3	—	ns
8	Output Hold Time from $\overline{\text{CAS}}$		t _{CHC}	5	—	5	—	ns
9	Output Buffer Turn On Delay Time		t _{ON}	0	—	0	—	ns
10	Output Buffer Turn Off Delay Time	*8	t _{OFF}	—	15	—	17	ns
11	Output Buffer Turn Off Delay Time from RAS	*8	t _{OFFR}	—	15	—	17	ns
12	Output Buffer Turn Off Delay Time from WE	*8	t _{WEZ}	—	15	—	17	ns
13	Transition Time		t _T	1	50	1	50	ns
14	$\overline{\text{RAS}}$ Precharge Time		t _{RP}	40	—	50	—	ns
15	$\overline{\text{RAS}}$ Pulse Width		t _{RAS}	60	100000	70	100000	ns
16	$\overline{\text{RAS}}$ Hold Time		t _{RSH}	15	—	17	—	ns
17	$\overline{\text{CAS}}$ to $\overline{\text{RAS}}$ Precharge Time		t _{CRP}	5	—	5	—	ns
18	$\overline{\text{CAS}}$ to $\overline{\text{RAS}}$ Delay Time	*9,10	t _{RCD}	14	45	14	53	ns
19	$\overline{\text{CAS}}$ Pulse Width		t _{CAS}	10	—	13	—	ns
20	$\overline{\text{CAS}}$ Hold Time		t _{CSH}	40	—	50	—	ns
21	$\overline{\text{CAS}}$ Precharge Time (Normal)	*17	t _{CPN}	10	—	10	—	ns
22	Row Address Set Up Time		t _{RSR}	0	—	0	—	ns
23	Row Address Hold Time		t _{RAH}	10	—	10	—	ns
24	Column Address Set Up Time		t _{ASC}	0	—	0	—	ns
25	Column Address Hold Time		t _{CAH}	10	—	10	—	ns
26	Column Address Hold Time from $\overline{\text{RAS}}$		t _{AR}	24	—	24	—	ns
27	$\overline{\text{RAS}}$ to Column Address Delay Time	*11	t _{RAD}	12	30	12	35	ns
28	Column Address to $\overline{\text{RAS}}$ Lead Time		t _{PAL}	30	—	35	—	ns
39	Column Address to $\overline{\text{CAS}}$ Lead Time		t _{CAL}	23	—	28	—	ns
30	Read Command Set Up Time		t _{RCS}	5	—	5	—	ns
31	Read Command Hold Time Referenced to $\overline{\text{RAS}}$	*12	t _{RRH}	0	—	0	—	ns

(Continued)

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No.	Parameter	Notes	Symbol	MB8502E064AA-60/-60L		MB8502E064AA-70/70L		Unit
				Min.	Max.	Min.	Max.	
32	Read Command Hold Time Referenced to $\overline{\text{CAS}}$	*12	t _{RCH}	0	—	0	—	ns
33	Write Command Set Up Time	*13,18	t _{WCS}	0	—	0	—	ns
34	Write Command Hold Time		t _{WCH}	10	—	10	—	ns
35	Write Command Hold Time from $\overline{\text{RAS}}$		t _{WCR}	24	—	24	—	ns
36	$\overline{\text{WE}}$ Pulse Width		t _{WP}	10	—	10	—	ns
37	Write Command to $\overline{\text{RAS}}$ Lead Time		t _{RWL}	15	—	17	—	ns
38	Write Command to $\overline{\text{CAS}}$ Lead Time		t _{CWL}	10	—	13	—	ns
39	DIN Set Up Time		t _{DS}	0	—	0	—	ns
40	DIN Hold Time		t _{DH}	10	—	10	—	ns
41	Date Hold Time from $\overline{\text{RAS}}$		t _{DHR}	24	—	24	—	ns
42	$\overline{\text{RAS}}$ to $\overline{\text{WE}}$ Delay Time	*18	t _{RWD}	77	—	89	—	ns
43	$\overline{\text{CAS}}$ to $\overline{\text{WE}}$ Delay Time	*18	t _{CWD}	32	—	36	—	ns
44	Column Address to $\overline{\text{WE}}$ Delay Time	*18	t _{AWD}	47	15	54	—	ns
45	$\overline{\text{RAS}}$ Precharge Time to $\overline{\text{CAS}}$ Active Time (Refresh Cycles)		t _{RPC}	5	15	5	—	ns
46	$\overline{\text{CAS}}$ Set Up Time (C-B-R Refresh)		t _{CSR}	0	—	0	—	ns
47	$\overline{\text{CAS}}$ Hold Time (C-B-R Refresh)		t _{CHR}	10	—	12	—	ns
48	Access Time from $\overline{\text{OE}}$	*7	t _{OEA}	—	15	—	17	ns
49	Output Buffer Turn Off Delay from OE	*8	t _{OEZ}	—	15	—	17	ns
50	$\overline{\text{OE}}$ to $\overline{\text{RAS}}$ Lead Time for Valid Data		t _{OEL}	10	—	10	—	ns
51	$\overline{\text{OE}}$ to $\overline{\text{CAS}}$ Lead Time		t _{COL}	5	—	5	—	ns
52	$\overline{\text{OE}}$ Hold Time Referenced to $\overline{\text{WE}}$	*14	t _{OEH}	5	—	5	—	ns
53	$\overline{\text{OE}}$ to Data in Delay Time		t _{OED}	15	—	17	—	ns
54	$\overline{\text{RAS}}$ to Data in Delay Time		t _{RDD}	15	—	17	—	ns
55	$\overline{\text{CAS}}$ to Data in Delay Time		t _{CDD}	15	—	17	—	ns
56	DIN to $\overline{\text{CAS}}$ Delay Time	*15	t _{DZC}	0	—	0	—	ns
57	DIN to $\overline{\text{OE}}$ Delay Time	*15	t _{DZO}	0	—	0	—	ns
58	$\overline{\text{OE}}$ Precharge Time		t _{OEP}	8	—	8	—	ns
59	$\overline{\text{OE}}$ Hold Time Referenced to $\overline{\text{CAS}}$		t _{OECH}	10	—	10	—	ns
60	$\overline{\text{WE}}$ Precharge Time		t _{WPZ}	8	—	8	—	ns
61	$\overline{\text{WE}}$ to Data in Delay Time		t _{WED}	15	—	17	—	ns
62	Hyper Page Mode $\overline{\text{RAS}}$ Pulse/Width		t _{RASP}	—	100000	—	100000	ns

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(Continued)

No.	Parameter	Notes	Symbol	MB8502E064AA-60/-60L		MB8502E064AA-70/-70L		Unit
				Min.	Max.	Min.	Max.	
63	Hyper Page Mode Read/Write Cycle Time		t _{HPC}	25	—	30	—	ns
64	Hyper Page Mode Read-Modify-Write Cycle Time		t _{HPRWC}	69	—	79	—	ns
65	Access Time from $\overline{\text{CAS}}$ Precharge	*7,16	t _{CPA}	—	35	—	40	ns
66	Access Time from $\overline{\text{CAS}}$ Precharge Time		t _{CP}	10	—	10	—	ns
67	Hyper Page Mode $\overline{\text{RAS}}$ Hold Time from $\overline{\text{CAS}}$ Precharge		t _{RHCP}	35	—	40	—	ns
68	Hyper Page Mode $\overline{\text{CAS}}$ Precharge to $\overline{\text{WE}}$ Delay Time	*18	t _{CPWD}	52	—	59	—	ns
69	$\overline{\text{RAS}}$ Pulse Width (Self Refresh)	*19	t _{RASS}	100	—	100	—	μs
70	$\overline{\text{RAS}}$ Precharge Time (Self Refresh)	*19	t _{RPS}	104	—	124	—	ns
71	$\overline{\text{CAS}}$ Hold Time (Self Refresh)	*19	t _{CHS}	–50	—	–50	—	ns

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- Notes:**
- *1. An initial pause ($\overline{\text{RAS}} = \overline{\text{CAS}} = V_{\text{IH}}$) of 200 μs is required after power-up followed by any eight $\overline{\text{RAS}}$ -only cycles or eight $\overline{\text{CAS}}$ -before- $\overline{\text{RAS}}$ refresh cycles ($\overline{\text{WE}} = V_{\text{IH}}$) before proper device operation is achieved. If an internal refresh counter is used, a minimum of eight $\overline{\text{CAS}}$ -before- $\overline{\text{RAS}}$ initialization cycles are required instead of eight $\overline{\text{RAS}}$ cycles.
 - *2. AC characteristics assume $t_{\text{T}} = 5 \text{ ns}$.
 - *3. V_{IH} (min) and V_{IL} (max) are reference levels for measuring the timing of input signals. Transition times are measured between V_{IH} (min) and V_{IL} (max).
 - *4. Assumes that $t_{\text{RCD}} \leq t_{\text{RCD}} (\text{max})$, $t_{\text{RAD}} \leq t_{\text{RAD}} (\text{max})$. If t_{RCD} and/or t_{RAD} is greater than the maximum recommended value shown in this table, t_{RAC} will be increased by the amount that t_{RCD} exceeds the value shown.
 - *5. If $t_{\text{RCD}} \geq t_{\text{RCD}} (\text{max})$, $t_{\text{RAD}} \geq t_{\text{RAD}} (\text{max})$, and $t_{\text{ASC}} \geq t_{\text{AA}} - t_{\text{CAC}} - t_{\text{T}}$, access time is t_{CAC} .
 - *6. If $t_{\text{RAD}} \geq t_{\text{RAD}} (\text{max})$ and $t_{\text{ASC}} \leq t_{\text{AA}} - t_{\text{CAC}} - t_{\text{T}}$, access time is t_{AA} .
 - *7. Measured with a load equivalent to two TTL loads and 100 pF.
 - *8. t_{OFF} , t_{OEZ} , t_{OFR} and t_{WEZ} are specified that output buffer change to high-impedance state.
 - *9. Operation within the $t_{\text{RCD}} (\text{max})$ limit ensures that $t_{\text{RAC}} (\text{max})$ can be met. $t_{\text{RCD}} (\text{max})$ is specified as a reference point only; if t_{RCD} is greater than the specified $t_{\text{RCD}} (\text{max})$ limit, access time is controlled exclusively by t_{CAC} or t_{AA} .
 - *10. $t_{\text{RCD}} (\text{min}) = t_{\text{RAH}} (\text{min}) + 2t_{\text{T}} + t_{\text{ASC}} (\text{min})$.
 - *11. Operation within the $t_{\text{RAD}} (\text{max})$ limit ensures that $t_{\text{RAC}} (\text{max})$ can be met. $t_{\text{RAD}} (\text{max})$ is specified as a reference point only; if t_{RAD} is greater than the specified $t_{\text{RAD}} (\text{max})$ limit, access time is controlled exclusively by t_{CAC} or t_{AA} .
 - *12. Either t_{RRH} or t_{RCH} must be satisfied for a read cycle.
 - *13. t_{WCS} is specified as a reference point only. If $t_{\text{WCS}} \geq t_{\text{WCS}} (\text{min})$ the data output pin will remain High-Z state through entire cycle.
 - *14. Assumes that $t_{\text{WCS}} < t_{\text{WCS}} (\text{min})$.
 - *15. Either t_{DZC} or t_{DZO} must be satisfied.
 - *16. t_{CPA} is access time from the selection of a new column address (caused by changing $\overline{\text{CAS}}$ from "L" to "H"). Therefore, if t_{CP} become long, t_{CPA} also become longer than $t_{\text{CPA}} (\text{max})$.
 - *17. Assumes $\overline{\text{CAS}}$ -before- $\overline{\text{RAS}}$ refresh cycle.
 - *18. t_{WCS} , t_{CWD} , t_{RWD} , t_{AWD} , and t_{CPWD} are not restrictive operating parameters. They are included in the data sheets as an electrical characteristic only. If $t_{\text{WCS}} \geq t_{\text{WCS}} (\text{min})$, the cycle is an early write cycle and D_{OUT} pin will maintain high-impedance state throughout the entire cycle. If $t_{\text{CWD}} \geq t_{\text{CWD}} (\text{min})$, $t_{\text{RWD}} \geq t_{\text{RWD}} (\text{min})$, $t_{\text{AWD}} \geq t_{\text{AWD}} (\text{min})$, and $t_{\text{CPWD}} \geq t_{\text{CPWD}} (\text{min})$, the cycle is a read-modify-write cycle and data from the selected cell will appear at the D_{OUT} pin. If neither of the above conditions is satisfied, the cycle is a delayed write cycle and invalid data will appear the D_{OUT} pin, and write operation can be executed by satisfying t_{RWL} , t_{CWL} , t_{RAL} and t_{CAL} specifications.
 - *19. Assumes that Self Refresh.

*Source: See MB81V17805A Data Sheet for details on the electricals.

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■ SERIAL PRESENCE DETECT (SPD) FUNCTION

1. PIN DESCRIPTIONS

SCL (Serial Clock)

SCL input is used to clock all data input/output of SPD.

SDA (Serial Data)

SDA is a common pin used for all data input/output of SPD. The SDA pull-up resistor is required due to the open-drain output.

SA₀, SA₁, SA₂ (Address)

Address inputs are used to set the least significant three bits of the eight bits slave address. The address inputs must be fixed to select a particular module and the fixed address of each module must be different each other. For this module, any address inputs are not required because all addresses (SA₀, SA₁, SA₂) are driven to V_{SS} on the module.

2. SPD OPERATIONS

CLOCK and DATA CONVENTION

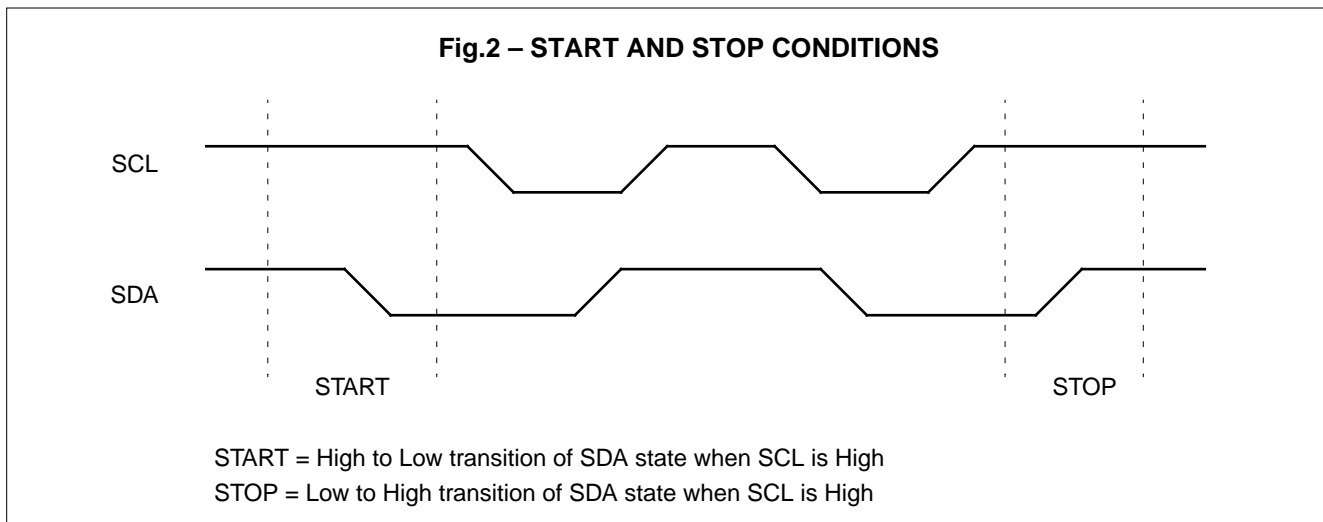
Data states on the SDA can change only during SCL=Low. SDA state changes during SCL=High are indicated start and stop conditions. Refer to Fig.2 below.

START CONDITION

All commands are preceded by a start condition, which is a transition of SDA state from High to Low when SCL=High. SPD will not respond to any command until this condition has been met.

STOP CONDITION

All read or write operation must be terminated by a stop condition, which is a transition of SDA state from Low to High when SCL=High. The stop condition is also used to make the SPD into the state of standby power mode after a read sequence.



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ACKNOWLEDGE

Acknowledge is a software convention used to indicate successful data transfer. The transmitting device, either master or slave, will release the bus after transmitting eight bits. During the ninth clock cycle the receiver will put the SDA line to Low in order to acknowledge that it received the eight bits of data.

The SPD will respond with an acknowledge when it received the start condition followed by slave address issued by master.

In the read operation, the SPD will transmit eight bits of data, release the SDA line and monitor the line for an acknowledge. If an acknowledge is detected and no stop condition is issued by master, the SPD will continue to transmit data. If an acknowledge is not detected, the SPD will terminated further data transmissions. The master must then issue a stop condition to return the SPD to the standby power mode.

In the write operation, upon receipt of eight bits of data the SPD will respond with an acknowledge, and await the next eight bits of data, again responding with an acknowledge until the stop condition is issued by master.

SLAVE ADDRESS ADDRESSING

Following a start condition, the master must output the eight bits slave address. The most significant four bits of the slave address are device type identifier. For the SPD this is fixed as 1010[B]. Refer to the Fig.3 below.

The next three significant bits are used to select a particular device. A system could have up to eight SPD devices –namely up to eight modules– on the bus. The eight addresses for eight SPD devices are defined by the state of the SA₀, SA₁ and SA₂ inputs. For this module, the three bits are fixed as 000[B] because all addresses are driven to V_{SS} on the module. Therefore, no address inputs are required.

The last bit of the slave address defines the operation to be performed. When R/ \bar{W} bit is “1”, a read operation is selected, when R/ \bar{W} bit is “0”, a write operation is selected.

Following the start condition, the SPD monitors the SDA line comparing the slave address being transmitted with its slave address (device type and state of SA₀, SA₁, and SA₂ inputs). Upon a correct compare the SPD outputs an acknowledge on the SDA line. Depending on the state of the R/ \bar{W} bit, the SPD will execute a read or write operation.

Fig.3 – SLAVE ADDRESS

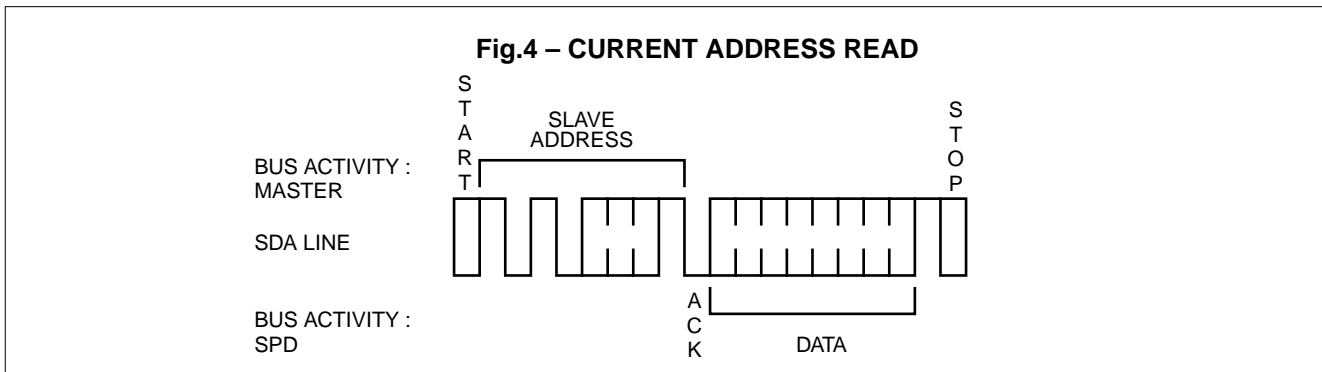
DEVICE TYPE IDENTIFIER				DEVICE ADDRESS			
1	0	1	0	SA ₂	SA ₁	SA ₀	R/ \bar{W}

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3. READ OPERATIONS

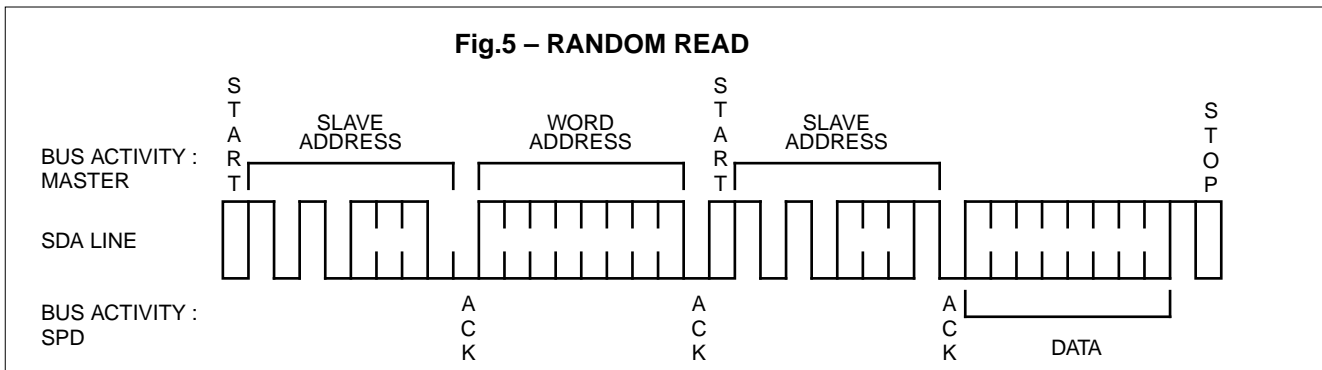
CURRENT ADDRESS READ

Internally the SPD contains an address counter that maintains the address of the last data accessed, incremented by one. Therefore, if the last access (either a read or write operation) was to address(n), the next read operation would access data from address(n+1). Upon receipt of the slave address with the R/\bar{W} bit = "1", the SPD issues an acknowledge and transmits the eight bits of data during the next eight clock cycles. The master terminates this transmission by issuing a stop condition, omitting the ninth clock cycle acknowledge. Refer to Fig.4 for the sequence of address, acknowledge and data transfer.



RANDOM READ

Random Read operations allow the master to access any memory location in a random manner. Prior to issuing the slave address with the R/\bar{W} bit = "1", the master must first perform a "dummy" write operation on the SPD. The master issues the start condition, and the slave address followed by the word address. After the word address acknowledge, the master immediately reissues the start condition and the slave address with the R/\bar{W} bit = "1". This will be followed by an acknowledge from the SPD and then by the eight bits of data. The master terminates this transmission by issuing a stop condition, omitting the ninth clock cycle acknowledge. Refer to Fig.5 for the sequence of address, acknowledge and data transfer.

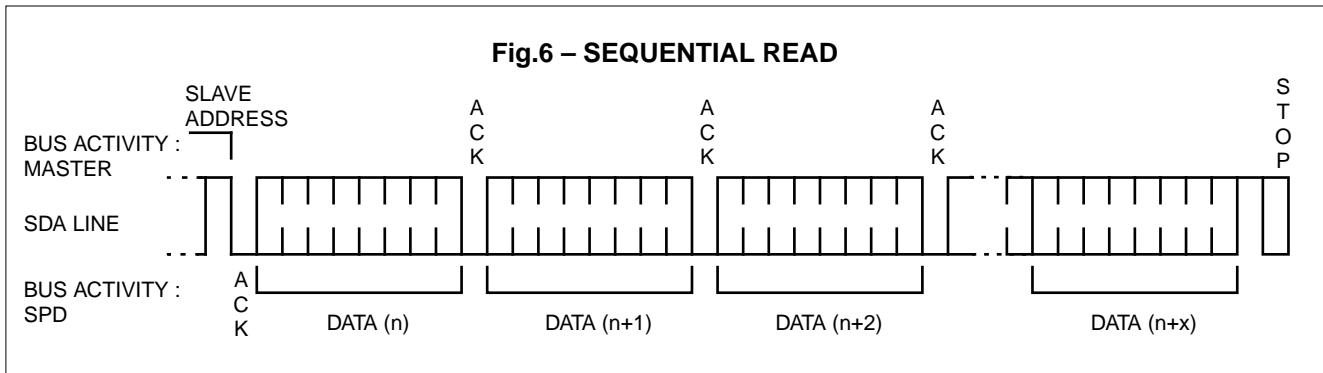


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SEQUENTIAL READ

Sequential Read can be initiated as either a current address read or random read. The first data are transmitted as with the other read mode, however, the master now responds with an acknowledge, indicating it requires additional data. The SPD continues to output data for each acknowledge received. The master terminates this transmission by issuing a stop condition, omitting the ninth clock cycle acknowledge. Refer to Fig.6 for the sequence of address, acknowledge and data transfer.

The data output is sequential, with the data from address(n) followed by the data from address(n+1). The address counter for read operations increments all address bits, allowing the entire memory contents to be serially read during one operation. At the end of the address space (address 255), the counter "rolls over" to address 0 and the SPD continues to output data for each acknowledge received.



4. DC CHARACTERISTICS

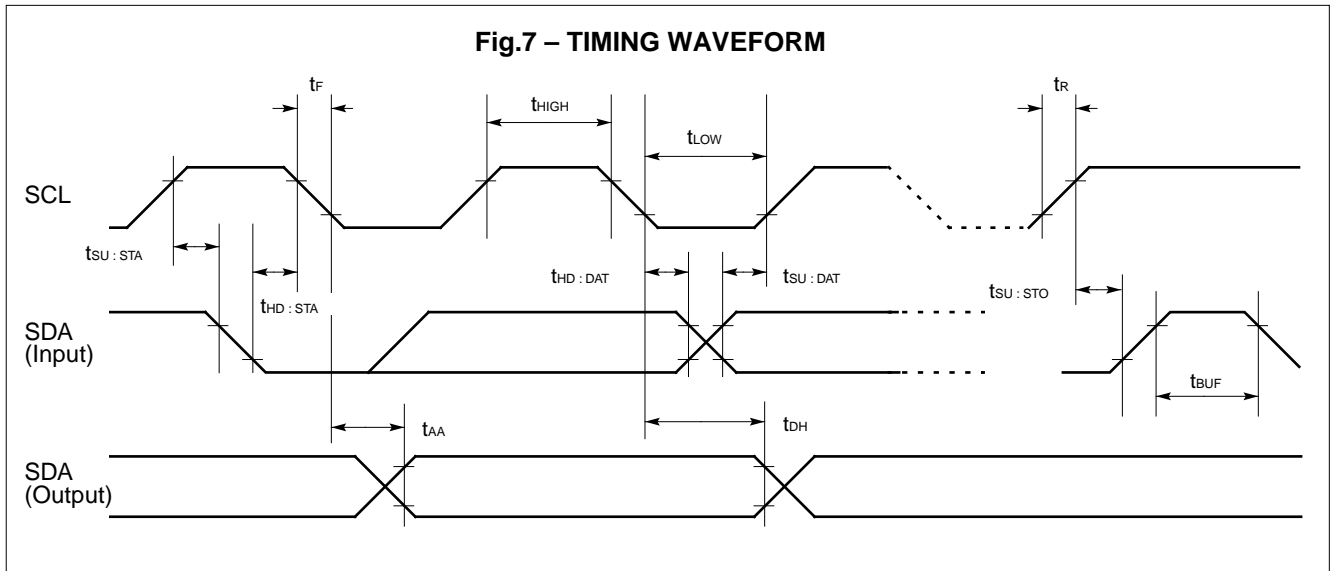
Parameter	Note	Test Condition	Symbol	Min.	Max.	Unit
Input Leakage Current		$0\text{ V} \leq V_{IN} \leq V_{CC}$	S_{ILI}	-10	10	μA
Output Leakage Current		$0\text{ V} \leq V_{OUT} \leq V_{CC}$	S_{ILO}	-10	10	μA
Output Low Voltage	*1	$I_{OL} = 3.0\text{ mA}$	S_{VOL}	—	0.4	V

Note: *1 Referenced to V_{SS} .

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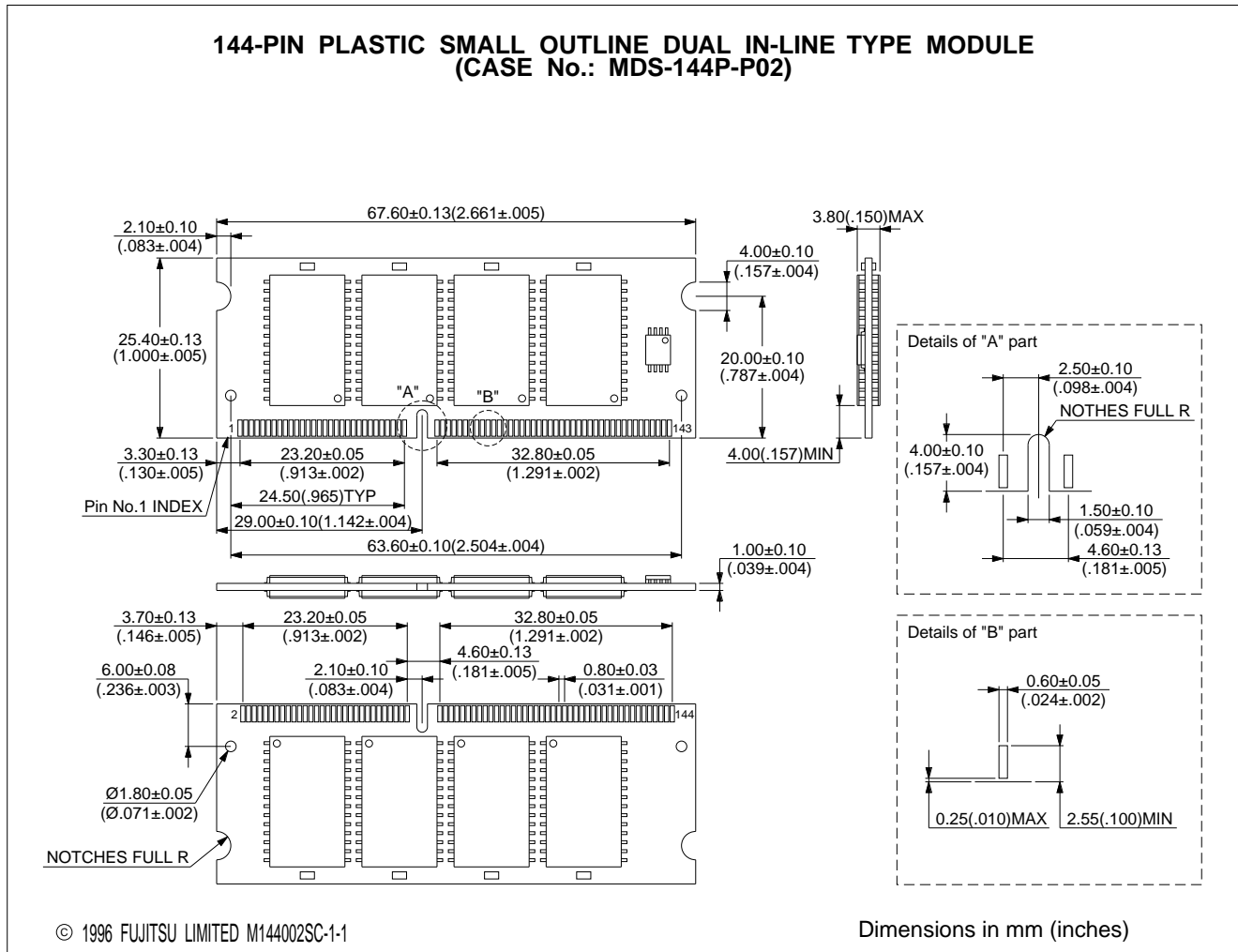
5. AC CHARACTERISTICS

No.	Parameter	Symbol	Min.	Max.	Unit
1	SCL Clock Frequency	f_{SCL}	0	100	KHz
2	Noise Suppression Time Constant at SCL, SDA Inputs	T_I	—	100	ns
3	SCL Low to SDA Data Out Valid	t_{AA}	0.3	3.5	μs
4	Time the Bus Must Be Free before a New Transmission Can Start	t_{BUF}	4.7	—	μs
5	Start Condition Hold Time	$t_{HD: STA}$	4.0	—	μs
6	Clock Low Period	t_{LOW}	4.7	—	μs
7	Clock High Period	t_{HIGH}	4.0	—	μs
8	Start Condition Set Up Time	$t_{SU: STA}$	4.7	—	μs
9	Data In Hold Time	$t_{HD: DAT}$	0	—	μs
10	Data In Set Up Time	$t_{SU: DAT}$	250	—	μs
11	SDA and SCL Rise Time	t_R	—	1	μs
12	SDA and SCL Fall Time	t_F	—	300	ns
13	Stop Condition Set Up Time	$t_{SU: STO}$	4.7	—	μs
14	Data Out Hold Time	t_{DH}	100	—	ns
15	Write Cycle Time	t_{WR}	—	15	ms



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■ PACKAGE DIMENSIONS



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